1.8V Drive Nch+SBD MOSFET

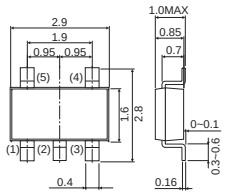
QS5U34

●Structure
Silicon N-channel MOSFET
Schottky Barrier DIODE

●Features
1) The QS5U34 combines Nch MOSFET with a Schottky barrier diode in a single TSMT5 package.
2) Low on-state resistance with fast switching.
3) Low voltage drive (1.8V).
4) The Independently connected Schottky barrier diode has low forward voltage.

●Dimensions (Unit : mm)

TSMT5



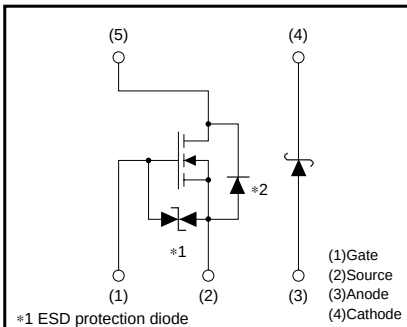
Each lead has same dimensions
Abbreviated symbol : U34

●Applications
Load switch, DC / DC conversion

●Packaging specifications

Type	Package	Taping
	Code	TR
	Quantity (pcs)	3000
QS5U34		◯

●Equivalent circuit



*1 ESD protection diode
*2 Body diode

●Absolute maximum ratings (Ta=25°C)

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Parameter		Symbol	Limits	Unit
Drain-source voltage		V_{DSS}	20	V
Gate-source voltage		V_{GSS}	10	V
Drain current	Continuous	I_D	±1.5	A
	Pulsed	I_{DP} *1	±3.0	A
Source current (Body diode)	Continuous	I_S	0.6	A
	Pulsed	I_{SP} *1	2.4	A
Channel temperature		Tch	150	°C
Power dissipation		P_D *3	0.9	W/ELEMENT

<Di>

Repetitive peak reverse voltage	V_{RM}	30	V
Reverse voltage	V_R	20	V
Forward current	I_F	0.5	A
Forward current surge peak	I_{FSM} *2	2.0	A
Junction temperature	Tj	150	°C
Power dissipation	P_D *3	0.7	W/ELEMENT

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Total power dissipation	P_D *3	1.25	W / TOTAL
Range of Storage temperature	Tstg	−55 to +150	°C

*1 Pw≤10μs, Duty cycle≤1% *2 60Hz・1cyc. *3 Mounted on a ceramic board

●Electrical characteristics (Ta=25°C)

<MOSFET>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I_{GSS}	–	–	10	μA	V_{GS}=10V / V_{DS}=0V
Drain-source breakdown voltage	$V_{(BR)\ DSS}$	20	–	–	V	I_D=1mA, / V_{GS}=0V
Zero gate voltage drain current	I_{DSS}	–	–	1	μA	V_{DS}=20V / V_{GS}=0V
Gate threshold voltage	$V_{GS\ (th)}$	0.3	–	1.3	V	V_{DS}=10V / I_D=1mA
Static drain-source on-state resistance	$R_{DS\ (on)}$*	–	130	180	mΩ	I_D=1.5A, V_{GS}=4.5V
		–	170	240	mΩ	I_D=1.5A, V_{GS}=2.5V
		–	220	310	mΩ	I_D=0.8A, V_{GS}=1.8V
Forward transfer admittance	$\|Y_{fs}\|$ *	1.6	–	–	S	V_{DS}=10V, I_D=1.5A
Input capacitance	C_{iss}	–	110	–	pF	V_{DS}=10V
Output capacitance	C_{oss}	–	18	–	pF	V_{GS}=0V
Reverse transfer capacitance	C_{rss}	–	15	–	pF	f=1MHz
Turn-on delay time	$t_{d\ (on)}$ *	–	5	–	ns	I_D=1.0A
Rise time	t_r *	–	5	–	ns	V_{DD}≒10V
Turn-off delay time	$t_{d\ (off)}$ *	–	20	–	ns	V_{GS}=4.5V
Fall time	t_f *	–	3	–	ns	R_L=10Ω
						R_G=10Ω
Total gate charge	Q_g *	–	1.8	2.5	nC	V_{DD}≒10V
Gate-source charge	Q_{gs} *	–	0.3	–	nC	V_{GS}=4.5V
Gate-drain charge	Q_{gd} *	–	0.3	–	nC	I_D=1.5A

*Pulsed

<MOSFET>Body diode (source-drain)

Forward voltage	V_{SD}	–	–	1.2	V	I_S=0.6A / V_{GS}=0V

<Di>

Forward voltage	V_F	–	–	0.36	V	I_F=0.1A
		–	–	0.47	V	I_F=0.5A
Reverse current	I_R	–	–	100	μA	V_R=20V

●Electrical characteristic curves

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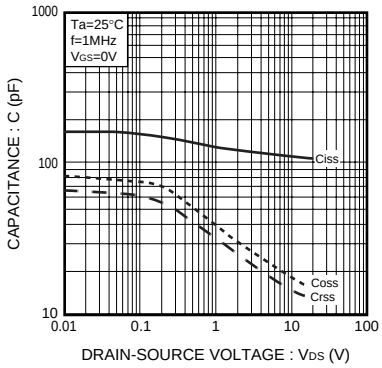

Fig.1 Typical Capacitance vs. Drain-Source Voltage

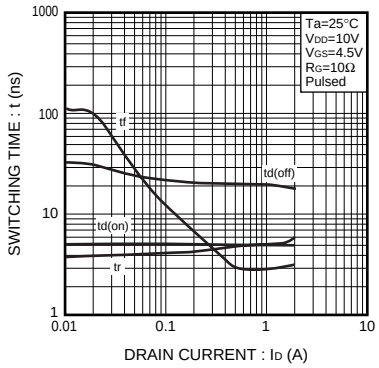

Fig.2 Switching Characteristics

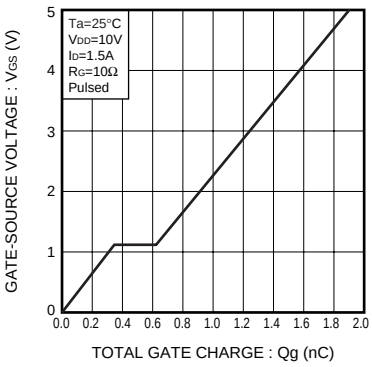

Fig.3 Dynamic Input Characteristics

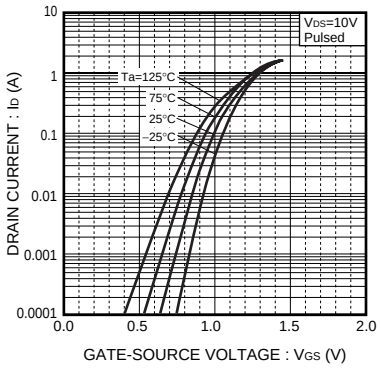

Fig.4 Typical Transfer Characteristics

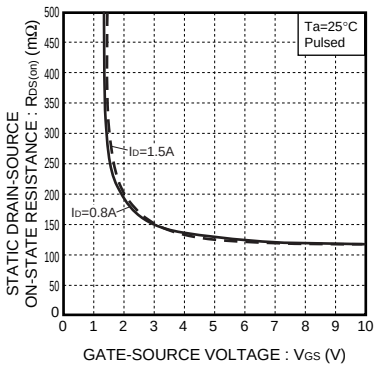

Fig.5 Static Drain-Source On-State Resistance vs. Gate-source Voltage

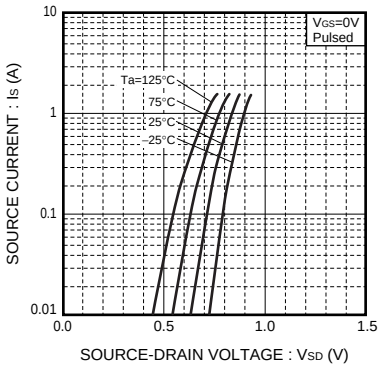

Fig.6 Source Current vs. Source-Drain Voltage

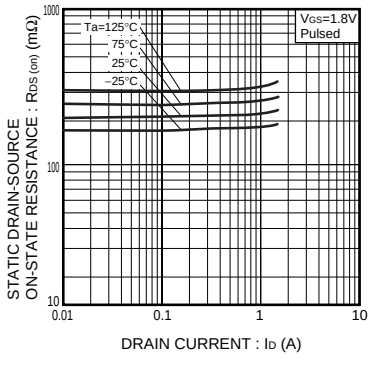

Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (Ⅰ)

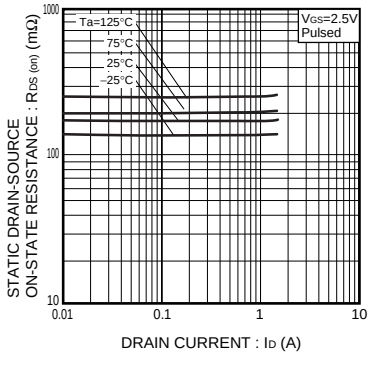

Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (Ⅱ)

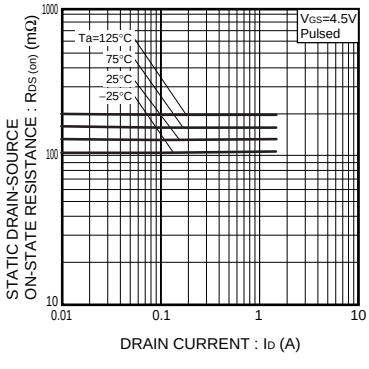

Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (Ⅲ)

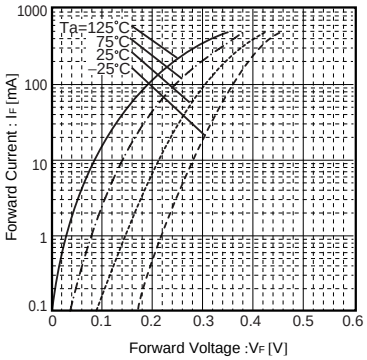

Fig.10 Forward Temperature Characteristics

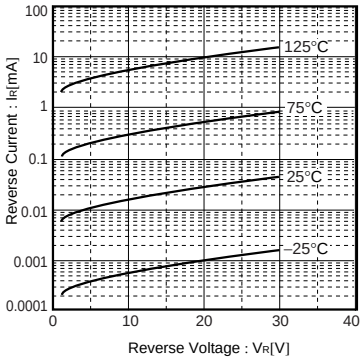

Fig.11 Reverse Temperature Characteristics

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASSⅡb	CLASSⅢ
CLASSⅣ		CLASSⅢ	

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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   [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
   [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl_2, H_2S, NH_3, SO_2, and NO_2
   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.) ; or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.

2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
   [a] the Products are exposed to sea winds or corrosive gases, including Cl_2, H_2S, NH_3, SO_2, and NO_2
   [b] the temperature or humidity exceeds those recommended by ROHM
   [c] the Products are exposed to direct sunshine or condensation
   [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

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